IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved u international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1					Form Type Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					iterials and	ials and Mfg Information				
Supplier	Information															
Company	name*	Company uni	Company unique ID			Unique ID Authority					Respo	Response Date*				
onsemi											2025-	2025-07-13				
Contact N	ame	Title - Contact]	Phone - Contact*					Email	Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA					Prod	Product-Env-Stewards@onsemi.com			
Authorize	d Representative*	Title - Representative]	Phone - Representative*				Email	Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA					Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective D	Pate Version Manufacturing Site		;	Weight	t*	UOM	Unit Type		
		NCV4275ADT50RKG 450 MA LDO, 5V				2025-07-13	3	MY1			350.99 mg		mg	Each		
Manufa	cturing Proccess Informat	ion														
	Terminal Plating / Grid Array Ma	Terminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Tempera		perature	ture Max Time at Peak Temp		rature 1	Number (of Reflow Cyc	es			
Matte Tin (Sn) - annealed		CU Alloy 1			260 C		2	30	sec	onds 3	3					
Comments																
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds												
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed								
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted								
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the								
Supplier Digital Signature Ra	astislav Drska	-En										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	A	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64		Supplier	Iron (Fe)	7439-89-6		0.2146	mg
			Supplier	Copper (Cu)	7440-50-8		214.361	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0644	mg
Mold Compound-Black	129.65			Phenolic Resin	proprietary data		10.372	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		108.2577	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg